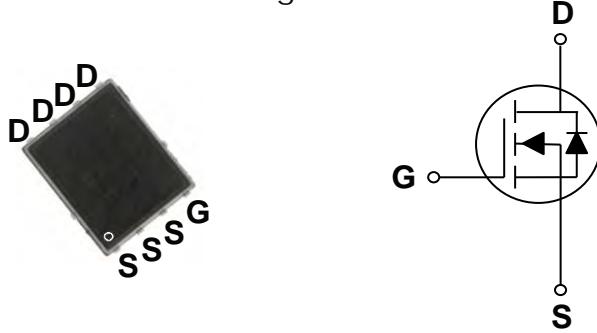


30V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

PPAK5x6 Pin Configuration



BVDSS	RDS(ON)	ID
30V	1.6mΩ	130A

Features

- 30V, 130A, RDS(ON) = 1.6mΩ @ VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Server Vcore
- POL Applications
- SMPS 2nd SR
- BMS System

Absolute Maximum Ratings T_c=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous (T _c =25°C)	130	A
	Drain Current – Continuous (T _c =100°C)	82	A
I _{DM}	Drain Current – Pulsed ¹	520	A
EAS	Single Pulse Avalanche Energy ²	245	mJ
IAS	Single Pulse Avalanche Current ²	70	A
P _D	Power Dissipation (T _c =25°C)	166	W
	Power Dissipation – Derate above 25°C	1.33	W/°C
T _{STG}	Storage Temperature Range	-55 to 175	°C
T _J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	0.9	°C/W

30V N-Channel MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Static State Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=27\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=85^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ³	$V_{\text{GS}}=10\text{V}$, $I_D=30\text{A}$	---	1.2	1.6	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=15\text{A}$	---	1.8	2.4	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1	1.6	2.5	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=15\text{A}$	---	30	---	S

Dynamic Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	---	65	120	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	16	30	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	21	40	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{3, 4}	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$	---	28	56	ns
T_r	Rise Time ^{3, 4}		---	45	90	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{3, 4}		---	105	200	
T_f	Fall Time ^{3, 4}		---	40	80	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	7720	11000	pF
C_{oss}	Output Capacitance		---	945	1400	
C_{rss}	Reverse Transfer Capacitance		---	435	650	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	1.2	2.4	Ω

Guaranteed Avalanche Energy

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	$V_{\text{DD}}=25\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=30\text{A}$	45	---	---	mJ

Drain-Source Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	130	A
I_{SM}	Pulsed Source Current ³		---	---	260	A
V_{SD}	Diode Forward Voltage ³	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=70\text{A}$, $R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.

30V N-Channel MOSFETs

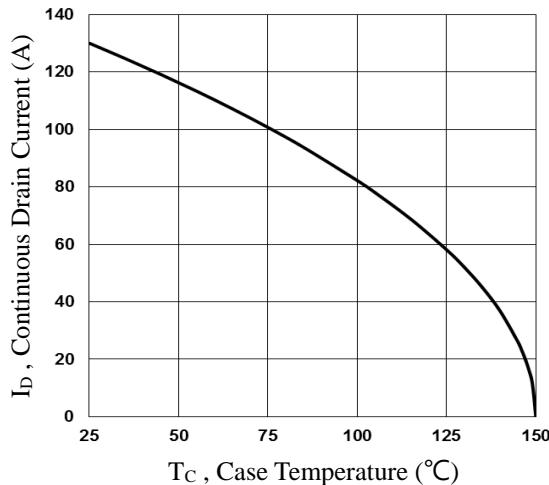


Fig.1 Continuous Drain Current vs. T_C

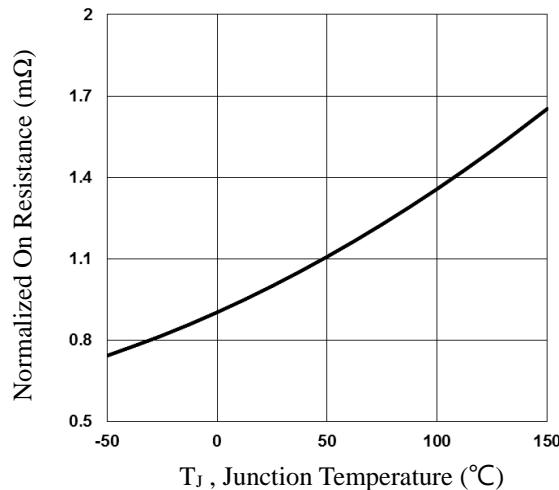


Fig.2 Normalized RDSON vs. T_J

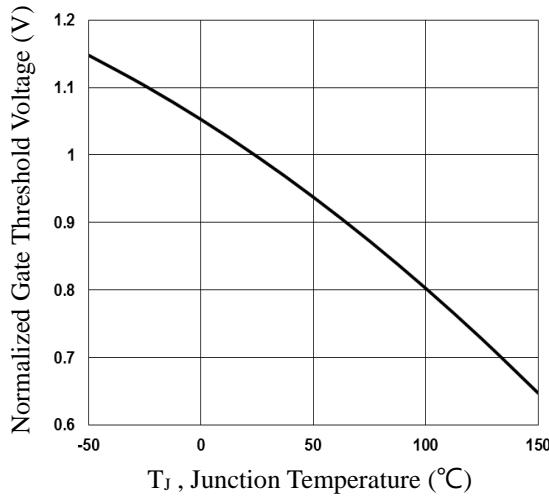


Fig.3 Normalized V_{th} vs. T_J

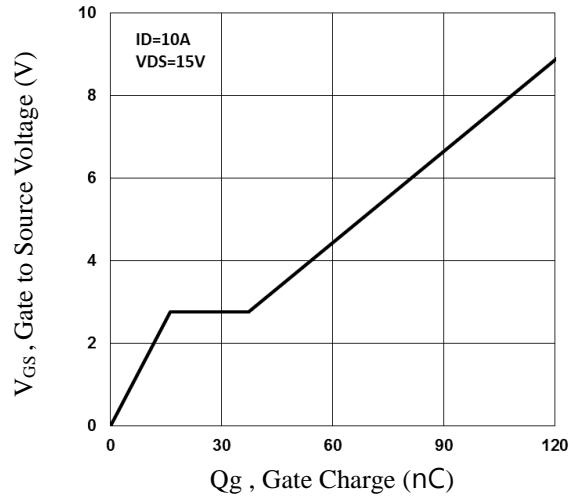


Fig.4 Gate Charge Waveform

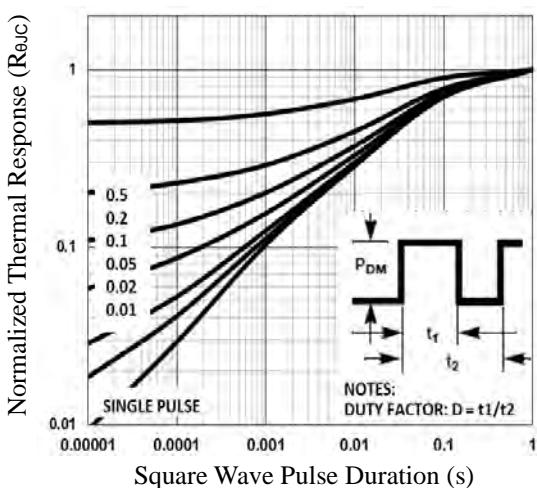


Fig.5 Normalized Transient Impedance

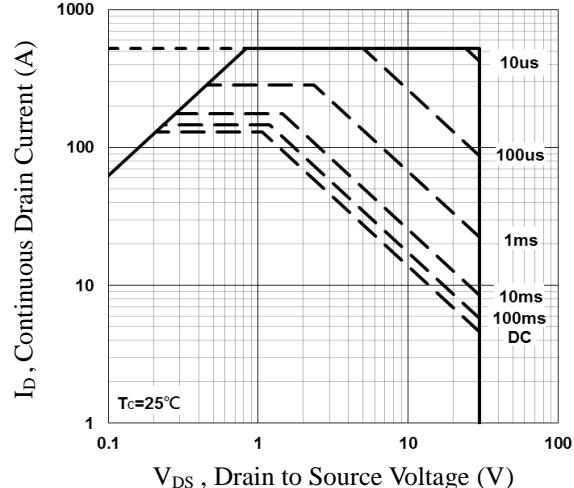


Fig.6 Maximum Safe Operation Area

30V N-Channel MOSFETs

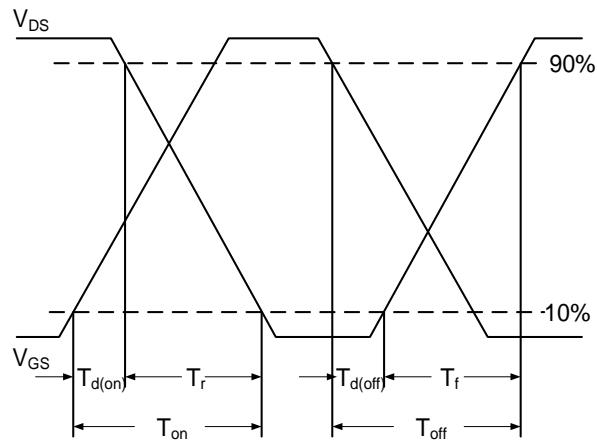


Fig.7 Switching Time Waveform

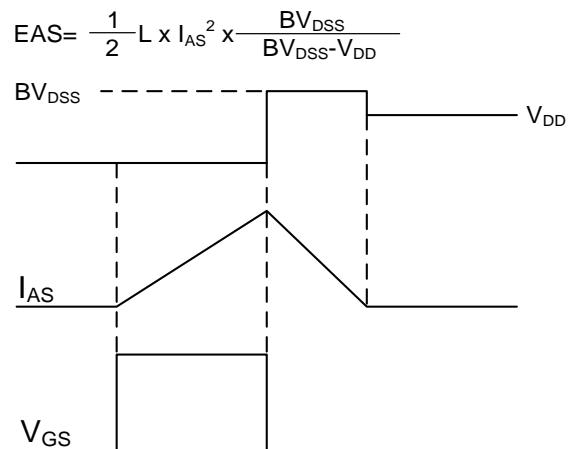
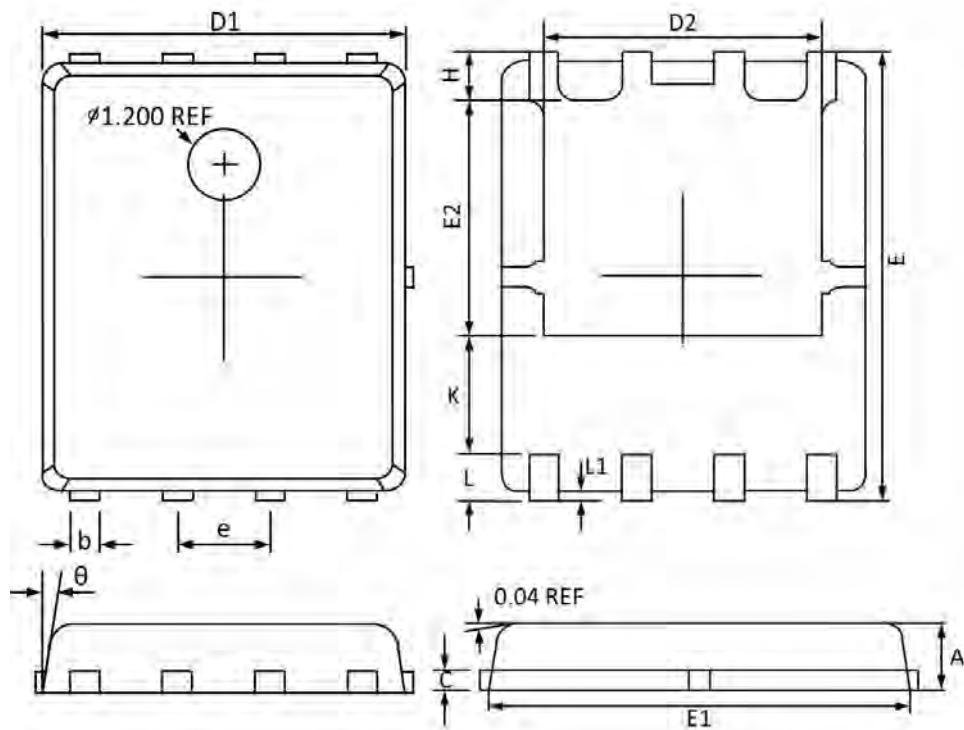


Fig.8 EAS Waveform

30V N-Channel MOSFETs

PPAK5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°